

**Product Change Notification - KSRA-25RBZL044**


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**Date:**

07 Nov 2019

**Product Category:**

Access Networks; Voice Audio

**Affected CPNs:**

**Notification subject:**

CCB 3997, 3997.001 and 3997.002 Initial Notice: Qualification of MMT as a new assembly site for selected MSCC products of LE79RXXX, MT093XXX, MT88XXX, MT89XXX, MT91XXX and ZL50XXX device families available in 28L (11.5x11.5x4.4mm), 32L PLCC (11.5x14x3.37mm) and 44L PLCC (16.6x16.6x4.4mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire

**Notification text:**
**PCN Status:**

Initial notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of MMT as a new assembly site for selected MSCC products of LE79RXXX, MT093XXX, MT88XXX, MT89XXX, MT91XXX and ZL50XXX device families available in 28L (11.5x11.5x4.4mm), 32L PLCC (11.5x14x3.37mm) and 44L PLCC (16.6x16.6x4.4mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire

**Pre Change:**

Assembled at ASEM assembly site copper (Cu) bond wire, YIZ8143 die attach and CEL 9240HF10AK-G1 molding compound material

**Post Change:**

Assembled at MMT assembly site using palladium coated copper with gold flash (CuPdAu) bond wire 3280 die attach and G600V molding compound material

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	ASE Group -Malaysia / ASEM	Microchip Technology Thailand (Branch) / MMT
<b>Wire material</b>	Cu wire	CuPdAu Wire
<b>Die attach material</b>	YIZ8143	3280
<b>Molding compound material</b>	CEL 9240HF10AK-G1	G600V
<b>Lead frame material</b>	A194	A194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability and on-time delivery by qualifying MMT as new assembly site

**Change Implementation Status:**



In Progress

**Estimated Qualification Completion Date:**

January 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	November 2019					-->	January 2020				
	44	45	46	47	48		01	02	03	04	05
Workweek											
Initial PCN Issue Date		X									
Qual Report Availability								X			
Final PCN Issue Date								X			

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**

**November 07, 2019:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_KSRA-25RBZL044\\_Qual\\_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

LE79R70-1DJC  
LE79R70-1DJCT  
LE79R70DJC  
LE79R70DJCT  
LE79R79-1DJC  
LE79R79-1DJCT  
LE79R79-2DJC  
LE79R79-2DJCT  
LE79R79-3DJC  
LE79R79-3DJCT  
MT093AP1  
MT093APR1  
MT8806AP1  
MT8806APR1  
MT8808AP1  
MT8808APR1  
MT8809AP1  
MT8809APR1  
MT8812AP1  
MT8812APR1  
MT8815AP1  
MT8816AP1  
MT8816APR1  
MT8880CP1  
MT8880CPR1  
MT8888CP1  
MT8952BP1  
MT8952BPR1  
MT8980DP1  
MT8980DPR1  
MT8981DP1  
MT9171AP1  
MT9171APR1  
MT9172AP1  
MT9172APR1  
ZL50000DP1